RELIABILITY REPORT

FOR

MAX4364ESA

PLASTIC ENCAPSULATED DEVICES

July 8, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

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Quality Assurance
Executive Director
Conclusion

The MAX4364 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim’s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim’s quality and reliability standards.

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I. Device Description

A. General

The MAX4364 is a bridged audio power amplifier intended for portable audio devices with internal speakers. The MAX4364 is capable of delivering 1.4W from a single 5V supply and 500mW from a single 3V supply into an 8Ω load. The MAX4364 features 0.04% THD + N at 1kHz, 68dB PSRR at 217Hz and only 10nA of supply current in shutdown mode.

The MAX4364 bridged outputs eliminate the need for output-coupling capacitors, minimizing external component count. The MAX4364 also includes internal DC bias generation, clickless operation, short-circuit and thermal-overload protection. The devices is unity-gain stable, with the gain set by two external resistors.

The MAX4364 is available in a small 8-pin SO package.

B. Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Item</th>
<th>Rating</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCC, OUT_ to GND</td>
<td>-0.3V to +6V</td>
</tr>
<tr>
<td>IN+, IN-, BIAS, SHDN to GND</td>
<td>-0.3V to (VCC + 0.3V)</td>
</tr>
<tr>
<td>Output Short Circuit (OUT+ to OUT-) (Note 1)</td>
<td>Continuous</td>
</tr>
<tr>
<td>Junction Temperature</td>
<td>+150°C</td>
</tr>
<tr>
<td>Operating Temperature Range</td>
<td>-40°C to +85°C</td>
</tr>
<tr>
<td>Storage Temperature Range</td>
<td>-65°C to +150°C</td>
</tr>
<tr>
<td>Lead Temperature (soldering, 10s)</td>
<td>+300°C</td>
</tr>
<tr>
<td>Continuous Power Dissipation (TA = +70°C)</td>
<td>471mW</td>
</tr>
<tr>
<td>8-Pin NSO</td>
<td>5.88mW/°C</td>
</tr>
</tbody>
</table>

Note 1: Continuous power dissipation must also be observed.
II. Manufacturing Information

A. Description/Function: 1.4W, Ultra-Small, Audio Power Amplifiers with Shutdown

B. Process: B8 (Standard 0.8 micron silicon gate CMOS)

C. Number of Device Transistors: 772

D. Fabrication Location: California, USA

E. Assembly Location: Malaysia, Philippines or Thailand

F. Date of Initial Production: July, 2002

III. Packaging Information

A. Package Type: 8-Pin NSO

B. Lead Frame: Copper

C. Lead Finish: Solder Plate

D. Die Attach: Silver-filled Epoxy

E. Bondwire: Gold (1.3 mil dia.)

F. Mold Material: Epoxy with silica filler

G. Assembly Diagram: # 05-2501-0215

H. Flammability Rating: Class UL94-V0

I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112: Level 1

IV. Die Information

A. Dimensions: 75 x 82 mils

B. Passivation: Si$_3$N$_4$/SiO$_2$ (Silicon nitride/Silicon dioxide)

C. Interconnect: Aluminum/Si (Si = 1%)

D. Backside Metallization: None

E. Minimum Metal Width: 0.8 microns (as drawn)

F. Minimum Metal Spacing: 0.8 microns (as drawn)

G. Bondpad Dimensions: 5 mil. Sq.

H. Isolation Dielectric: SiO$_2$

I. Die Separation Method: Wafer Saw
V. Quality Assurance Information

A. Quality Assurance Contacts:  
Jim Pedicord (Reliability Lab Manager)  
Bryan Preeshl (Executive Director)  
Kenneth Huening (Vice President)

B. Outgoing Inspection Level:  
0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate:  < 50 ppm

D. Sampling Plan:  Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ($\lambda$) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 45 \times 2}$$

(Chi square value for MTTF upper limit)

\[\text{Temperature Acceleration factor assuming an activation energy of 0.8eV}\]

$$\lambda = 24.13 \times 10^{-9}$$

$$\lambda = 24.13 \text{ F.I.T.} \text{ (60% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim’s reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-5950) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (RR-1M).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The OX66 die type has been found to have all pins able to withstand a transient pulse of ±2000V per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.
<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>PACKAGE</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td>Static Life Test (Note 1)</td>
<td>Ta = 135°C</td>
<td>DC Parameters</td>
<td>45</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Biased</td>
<td>&amp; functionality</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Time = 192 hrs.</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Moisture Testing (Note 2)</td>
<td>Ta = 121°C</td>
<td>DC Parameters</td>
<td>NSO</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td></td>
<td>P = 15 psi.</td>
<td>&amp; functionality</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>RH = 100%</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Time = 168hrs.</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>85/85</td>
<td>Ta = 85°C</td>
<td>DC Parameters</td>
<td>77</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td></td>
<td>RH = 85%</td>
<td>&amp; functionality</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Biased</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Time = 1000hrs.</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Mechanical Stress (Note 2)</td>
<td>-65°C/150°C</td>
<td>DC Parameters</td>
<td>77</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td>Cycle</td>
<td>1000 Cycles</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Method 1010</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data
TABLE II. Pin combination to be tested. 1/ 2/

<table>
<thead>
<tr>
<th>Terminal A</th>
<th>Terminal B</th>
</tr>
</thead>
<tbody>
<tr>
<td>(Each pin individually connected to terminal A with the other floating)</td>
<td>(The common combination of all like-named pins connected to terminal B)</td>
</tr>
<tr>
<td>All pins except $V_{PS1}$ 3/</td>
<td>All $V_{PS1}$ pins</td>
</tr>
<tr>
<td>All input and output pins</td>
<td>All other input-output pins</td>
</tr>
</tbody>
</table>

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground (e.g., where $V_{PS1}$ is $V_{DD}$, $V_{CC}$, $V_{SS}$, $V_{BB}$, GND, $+V_S$, $-V_S$, $V_{REF}$, etc).

3.4 Pin combinations to be tested.

a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., $V_{SS1}$, or $V_{SS2}$ or $V_{SS3}$ or $V_{CC1}$, or $V_{CC2}$) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.
ONCE PER SOCKET

DEVICES: MAX 4364/4365

MAX. EXPECTED CURRENT = 20mA

NOTES:

ONCE PER BOARD

DRAWN BY: HAK TAN